

WIRE BONDING METHOD AND APPARATUS

ABSTRACT OF THE DISCLOSURE

5 A process and apparatus are described for wire bonding circuit devices of large scale integrated design. The bonding process employs a capillary tool that applies heat and pressure to the wires in order to bond them to the circuit device. The circuit device, or pad, is supported upon a closed woven, fiberglass mesh, which supports the circuit device during the bonding process.